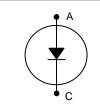
PCRKA20065F8M1

650 V, 200 A Extremefast Diode with Solderable Top Metal



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Features

- AEC-Q101 Qualified
- Maximum Junction Temperature 175°C
- Extremefast Technology with Soft Recovery
- Low Forward Voltage ($V_F = 1.35 \text{ V (Typ.)} \otimes I_F = 200 \text{ A}$)
- Cathode Pad covered with Solderable Metal Layer

Applications

- Automotive Traction Modules
- General Power Modules

ORDERING INFORMATION

Part Number	PCRKA20065F8M1				
Packing	Wafer (sawn on foil)				
	mils	μm			
Die Size	197 × 394	5,000 × 10,000			
Anode Area	183 × 381	4,668 × 9,668			
Die Thickness	3	78			
Top Metal	6 μm AlCu + 1.15 μm Ti/NiV/Ag (STM)				
Back Metal	0.65 μm NiV/Ag				
Topside Passivation	Silicon Nitride plus Polyimide				
Wafer Diameter	200 mm				
Max Possible Die Per Wafer	487				

PCRKA20065F8M1

ABSOLUTE MAXIMUM RATINGS ($T_{VJ} = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Ratings	Units	
Repetitive Peak Reverse Voltage	V_{RRM}	650	V	
DC Forward Current, limited by T _J max	I _F	(Note 1)	A	
Pulsed Forward Current, t _p limited by T _J max (Note 2)	I _{FM}	900	А	
Operating Junction Temperature	T _J	-40 to +175	°C	
Storage Temperature Range	T _{stg}	+17 to +25	°C	

ELECTRICAL CHARACTERISTICS OF THE DIODE ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Condition		Min.	Тур.	Max.	Units
Static Characteristics (Tested	d on wafers)						
Breakdown Voltage	V_{BR}	I _R = 1 mA		650	-	_	V
Reverse Leakage Current	I _R	V _R = 650 V		_	-	30	μΑ
Forward Voltage	V _F	I _F = 100 A		_	1.15	1.7	V
Electrical Characteristics (No	ot subject to production tes	t - verified by d	esign / characterization)	•	•	•	•
Forward Voltage	V _F	I _F = 200 A	T _J = 25°C	_	1.35	1.9	V
			T _J = 175°C	_	1.3	_	V
Reverse Recovery Charge	Q _{rr}	I _F = 200 A, V _R = 400 V dI _F /dt = 1000 A/μs, T _J = 25°C		_	3.2	_	μС
Reverse Recovery Current	I _{rr}			_	55	_	Α
Reverse Recovery Time	T _{rr}			_	117	_	ns
Reverse Recovery Charge	Q _{rr}	I _F = 200 A, V _R = 400 V dI _F /dt = 1000 A/μs, T _J = 175°C		_	15.1	-	μС
Reverse Recovery Current	I _{rr}				122		Α
Reverse Recovery Time	T _{rr}			_	247	_	nS

^{3.} For ordering, technique and other information on Onsemi automotive bare die products, please contact automotivebaredie@onsemi.com

Depends on the thermal properties of assembly
Not subject to production test – verified by design/characterization

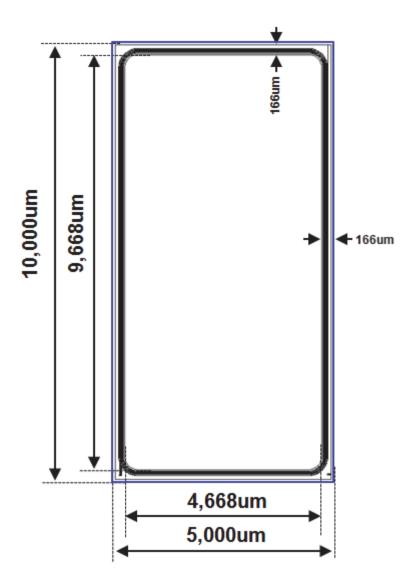


Figure 1. Dimensional Outline and Pad Layout

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